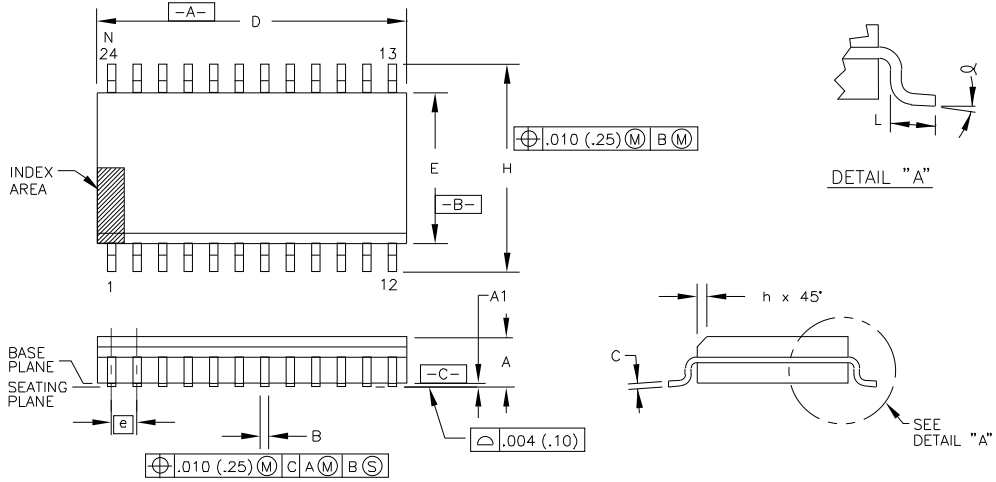


Package Number 239 - 24-Lead SOIC



DIM	INCHES		MILLIMETERS		N	E	DIM	INCHES		MILLIMETERS		N	E
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.		
A	.0926	.1043	2.35	2.65									
A1	.004	.0118	0.10	0.30									
B	.013	.020	0.33	0.51	7								
C	.0091	.0125	0.23	0.32									
D	.5985	.6141	15.20	15.60	2								
E	.2914	.2992	7.40	7.60	3								
e	.050	BASIC	1.27	BASIC									
H	.394	.419	10.00	10.65									
h	.010	.0295	0.25	0.75	4								
L	.016	.050	0.40	1.27	5								
N	24		24		6								
α	0°	8°	0°	8°									

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 IN. (0.15 mm) PER SIDE.
- DIMENSION E DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .010 IN. (0.25 mm) PER SIDE.
- THE CHAMFER ON THE BODY IS OPTIONAL. IF IT IS NOT PRESENT,

A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

- L IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
- N IS THE NUMBER OF TERMINAL POSITIONS.
- THE LEAD WIDTH B, AS MEASURED .014 IN. (0.36 mm) OR GREATER ABOVE THE SEATING PLANE, SHALL NOT EXCEED A MAXIMUM VALUE OF .024 IN. (0.61 mm).
- LEAD TO LEAD COPLANARITY SHALL BE LESS THAN .004 IN. (0.10 mm) FROM THE SEATING PLANE.

PACKAGE NUMBER: ZZZ39 REV.: E
JEDEC NUMBER: MS-D13-AD

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